

# *A Novel Silicon-Embedded Transformer for System-in-Package Power Isolation\**

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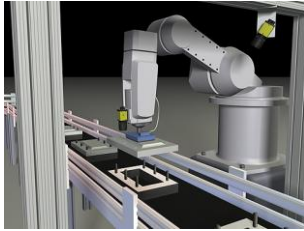
Madrid,  
October 2016

# Background

## ■ Signal & Small Power Isolation Applications

### Industrial:

Sensor  
Data Bus  
Motor Drive



### Automobile:

Motor Drive  
Battery Manage



### Power Generation:

PV Inverter  
Wind Turbine



### Telecom:

Data Bus  
PoE



### Medical:

Patient Monitor  
Sensor Probe



### Others:

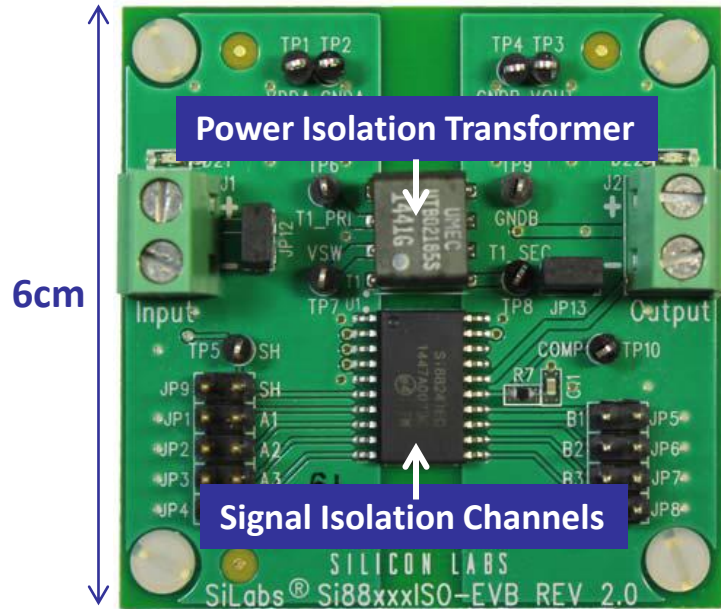
Instrumentation  
Consumer  
Aerospace



# Background

## ■ Small Power Isolation (<2W)

➤ Allow Simple Power Supply for Signal Isolation Channels



### Discrete Transformer Solution

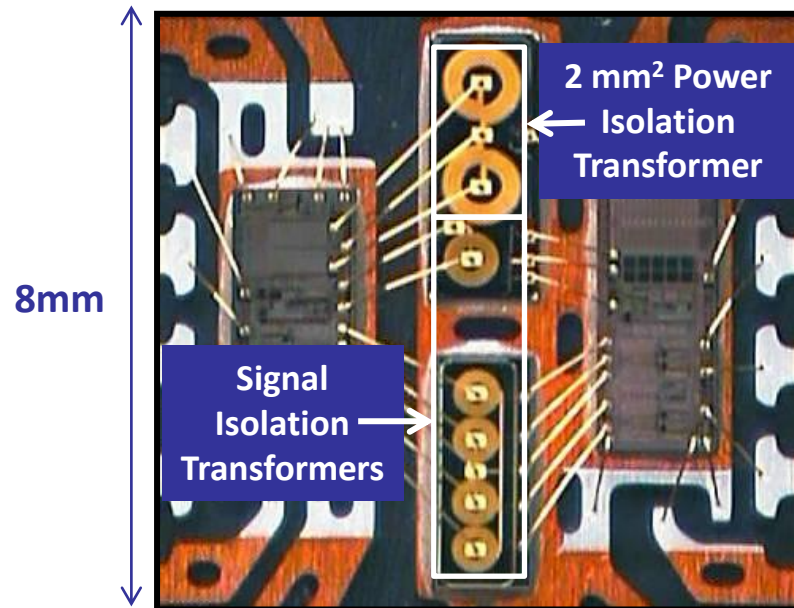
- ✓ 2 $\mu$ H/0.05 $\Omega$
- ✓ 200 kHz to 800 kHz
- ✓ Up to 78% dc-dc efficiency
- ✗ Low integration level
- ✗ Large solution size
- ✗ High system cost

Ref: Silicon Labs, Si88xxxISO-EVB

# Background

## ■ Small Power Isolation (<2W)

### ➤ Allow Simple Power Supply for Signal Isolation Channels



### On-Chip Transformer Solution

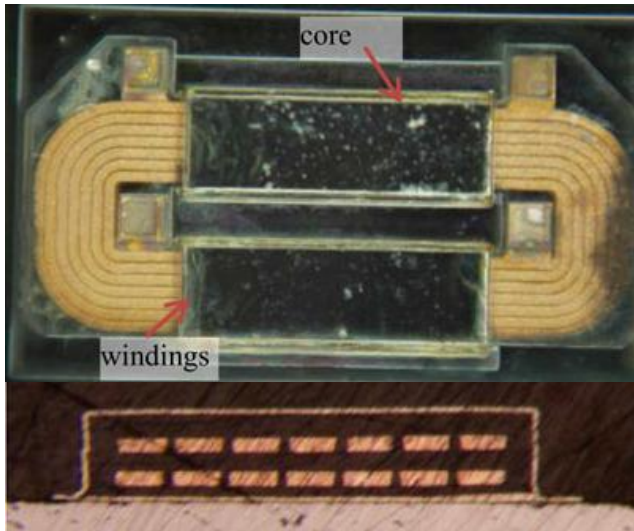
- ✓ System-in-package integration
- ✓ Small solution size
- ✓ Low system cost
- ✗ 16nH/1.6Ω
- ✗ 170 MHz
- ✗ Up to 34% dc-dc efficiency

Ref: Analog Devices, B. Chen, PwrSoC, 2008

# Background

## ■ Needed: High Performance On-Chip Transformers

➤ High Efficiency @ Low Frequency → Large L/R



### DLM Microtransformer

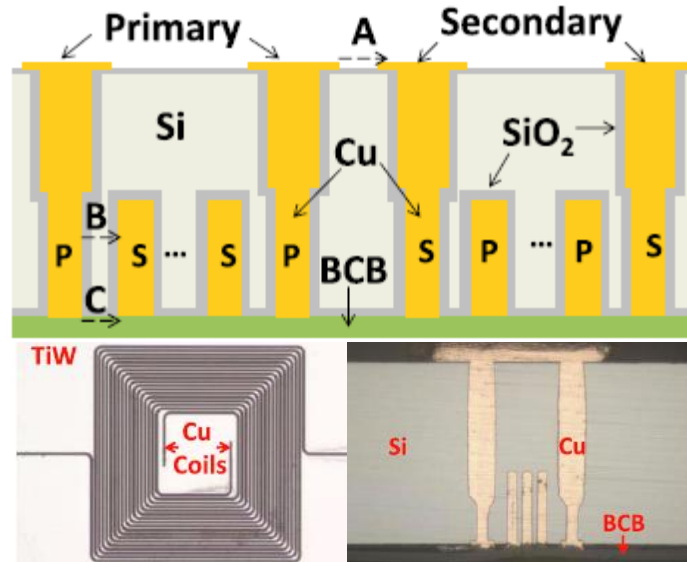
- ✓ 4.5  $\mu\text{m}$  core & 15  $\mu\text{m}$  metal
- ✓ 270 nH/1.22  $\Omega$
- ✓ 78% efficiency @ 20 MHz
- ✓ 6kV Isolation
- ✗ core related issues
- ✗ 7 masks
- ✗ 3 mm<sup>2</sup>

Ref: Tyndall, N. Wang et al., IEEE TPEL, 2015

# Background

## ■ Needed: High Performance On-Chip Transformers

➤ High Efficiency @ Low Frequency → Large L/R



## Interleaved Embedded Transformer

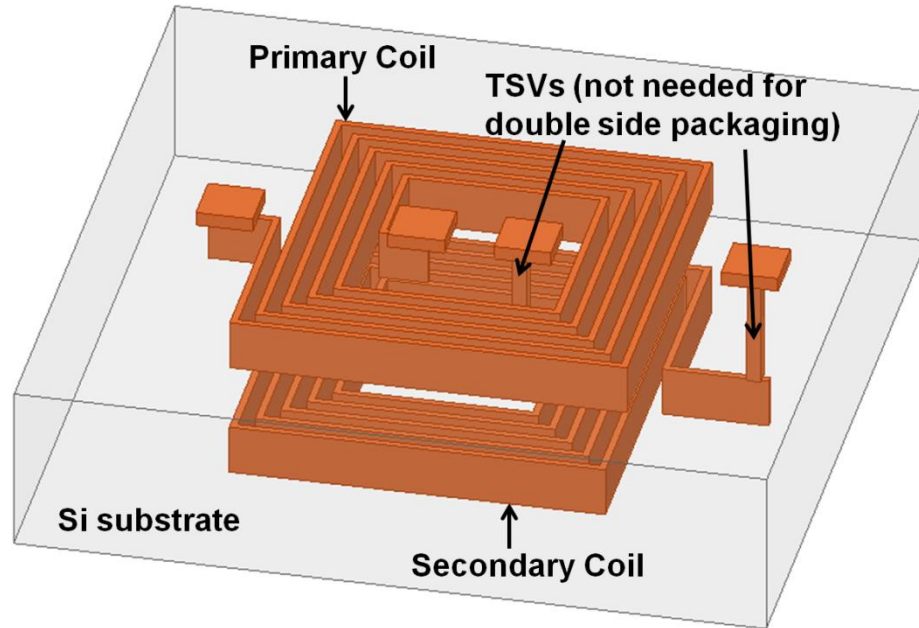
- ✓ 100 μm metal
- ✓ 88 nH/0.45 Ω
- ✓ 80% efficiency @ 20 MHz
- ✓ 3 masks
- ✓ 2 mm<sup>2</sup>
- ✗ 380 V isolation

breakdown path C at chip surface

Ref: Our Work, R. Wu et al., IEEE TED, 2015

# Double-Side Embedded Transformer

## ■ Device Structure



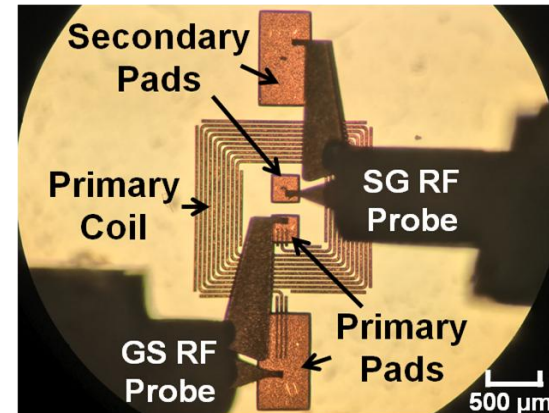
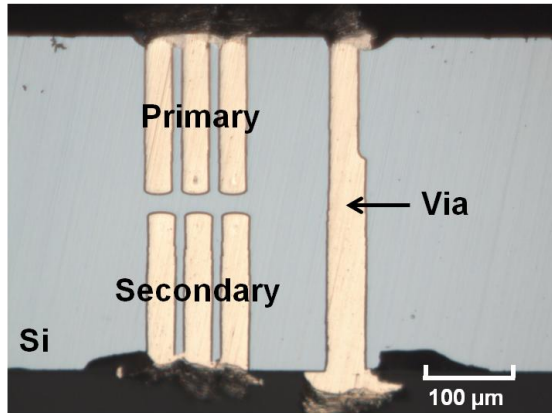
- ✓ large thicknesses for both coils
- ✓ whole area usage for both coils
- ✓ breakdown through substrate: Cu-oxide-Si-oxide-Cu for isolation
- ✓ balanced stresses at two sides
- ✗ weaker coupling

Ref: R. Wu et al., IEEE TED, in press

# Double-Side Embedded Transformer

## Transformer Design & Fabrication

Coil Diameter ( $\mu\text{m}$ )	Si Thickness ( $\mu\text{m}$ )	Cu Thickness ( $\mu\text{m}$ )	Track Width ( $\mu\text{m}$ )	Track Spacing ( $\mu\text{m}$ )	Number of Turns	Oxide Thickness ( $\mu\text{m}$ )
1400	350	150	22	15	9	2

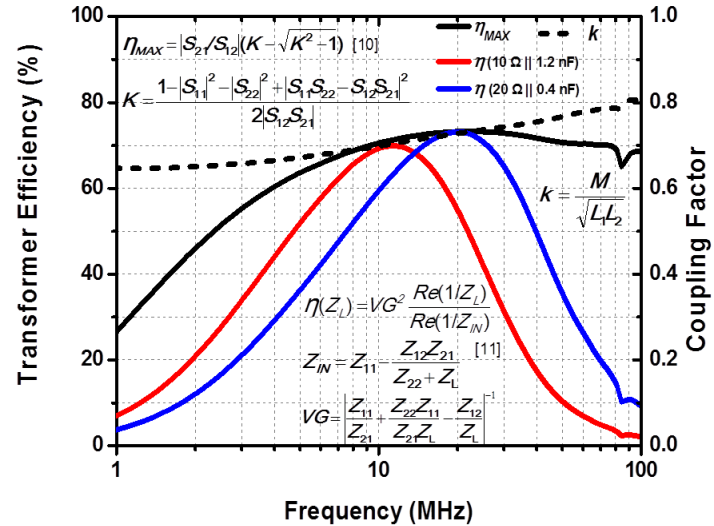
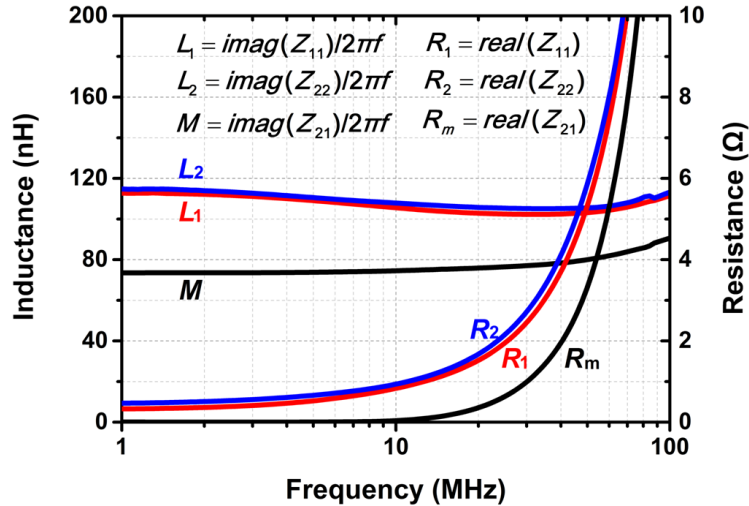


Ref: R. Wu et al., IEEE TED, in press



# Double-Side Embedded Transformer

## ■ Measurement Results



- 1050 V isolation for  $2 \times 2 \mu\text{m}$  thermal oxide isolation
- insulating substrate for further improving isolation capability

Ref: R. Wu et al., IEEE TED, in press

# Performance Comparison

	Coilcraft [1]	CityU [2]	ADI [3]	Tyndall [4]	Our Work [5]	This Work [6]
Technology	discrete	PCB	Si	Si	Si	Si
Magnetic Core	Yes	No	No	Yes	No	No
No. of Masks	N/A	N/A	5	7	3	4
Area (mm <sup>2</sup> )	23	21	2	3	2	2
Inductance (nH)	4700	242	16	270	88	113
Resistance ( $\Omega$ )	0.32	0.66	1.6	1.22	0.45	0.31
L/R ( $\mu\text{H}/\Omega$ )	14.7	0.37	0.01	0.22	0.20	0.36
Coupling	0.97	0.58	N/A	0.9	0.98	0.65
Efficiency	N/A	76%	70%	78%	80%	70%
Frequency (MHz)	1	8	170	20	20	10
Isolation (kV)	1.5	15	7	6	0.38	1.05

[1] Coilcraft: “Miniature transformers LPD5030V,” Revised 2015.

[2] CityU: S.C. Tang et al., IEEE Transactions on Power Electronics, pp. 311-315, 2001.

[3] ADI: B. Chen, PwrSoC, 2008; ADuM6000 Datasheet ,Revised 2013.

[4] Tyndall: N. Wang et al., IEEE Transactions on Power Electronics, pp. 5746-5754, 2015.

[5] Our Work: R. Wu et al., IEEE Transactions on Electron Devices, pp. 220-223, 2015.

[6] This Work: R. Wu et al., “A Novel Double-Side Silicon-Embedded Transformer for 10-MHz, 1-kV-Isolation, Compact Power Transfer Applications,” IEEE Transactions on Electron Devices, in press

# Conclusions

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- On-chip transformers with high efficiencies at low frequency are needed for compact, low cost, system-in-package isolated power supply (<2W).
- The double-side embedded transformer features large thicknesses and whole area utilization for both coils. It achieved a best reported L/R of  $0.36 \mu\text{H}/\Omega$  with an area of  $2 \text{ mm}^2$ . Consequently it can work at a low frequency of 10 MHz with a reasonable efficiency of 70%.
- The only breakdown path is through the substrate. An isolation capability of 1050 V was achieved with two 2- $\mu\text{m}$ -thick thermal oxide isolation layers, and can be further improved by using an insulating substrate.